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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Chi-Hsing Hsu

Serial No.: 10/063,572

Filed: May 3, 2002

For: Wafer level packaging and chip
structure

Examiner: Gurley, Lynne Ann

Art Unit: 2812

Docket No.: 8289-US-PA

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on

Signature

AMENDMENT AND RESPONSE TO OFFICE ACTION

Assistant Commissioner of Patents and Trademarks
Washington, DC 20231

Sir:

The Office Action dated December 4, 2002 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

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